

*-30V Dual P-Channel Enhancement Mode MOSFET*

❖ *DESCRIPTION*

The AM4953 is the Dual P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application, notebook computer power management and other battery powered circuits where high-side switching.

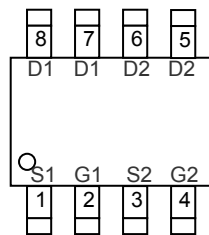
❖ *APPLICATIONS*

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

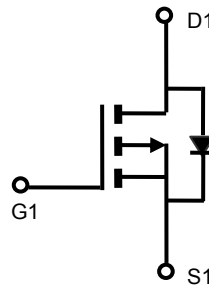
❖ *FEATURE*

- **-30V/-5.2A,  $R_{DS(ON)} < 60m\Omega @ V_{GS} = -10V$**
- **-30V/-4.5A,  $R_{DS(ON)} < 90m\Omega @ V_{GS} = -4.5V$**
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- Full RoHS compliance
- SOP-8 package design

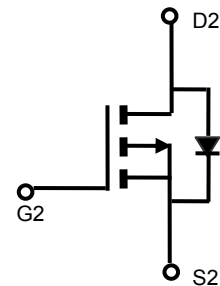
❖ *PIN CONFIGURATION*



TOP VIEW  
SOP-8

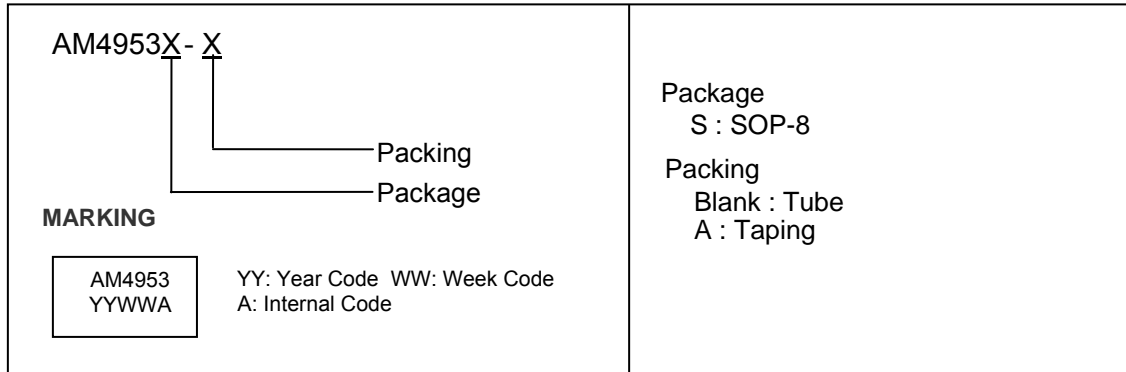


P-Channel



P-Channel

❖ PART MARKING INFORMATION



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Part Number	Package Code	Package	Shipping
AM4953S-A	S	SOP-8	2500 /Tape&Reel

- ※ Year Code : 00 ~ 99
- ※ Week Code : 01~52
- ※ SOP-8 : Only available in tape and reel packaging. (A reel contains 2500 devices)
- ※ G : Lead-free product. This product is RoHS compliant

❖ ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$  Unless otherwise noted)

Symbol	Parameter	Typical	Unit
V <sub>DSS</sub>	Drain-Source Voltage	-30	V
V <sub>GSS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current (T <sub>J</sub> =150°C)	V <sub>Gs</sub> = -10V	A
I <sub>DM</sub>	Pulsed Drain Current	-20	A
I <sub>S</sub>	Continuous Source Current (Diode Conduction)	-2.4	A
T <sub>J</sub>	Operation Junction Temperature	-55~150	°C
T <sub>STG</sub>	Storage Temperature Range	-55~150	°C
P <sub>D</sub>	Power Dissipation	T <sub>A</sub> =25°C T <sub>A</sub> =70°C	2.8 1.8 W
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient	70	°C/W

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.  
Absolute maximum ratings are stress ratings only and functional device operation is not implied.

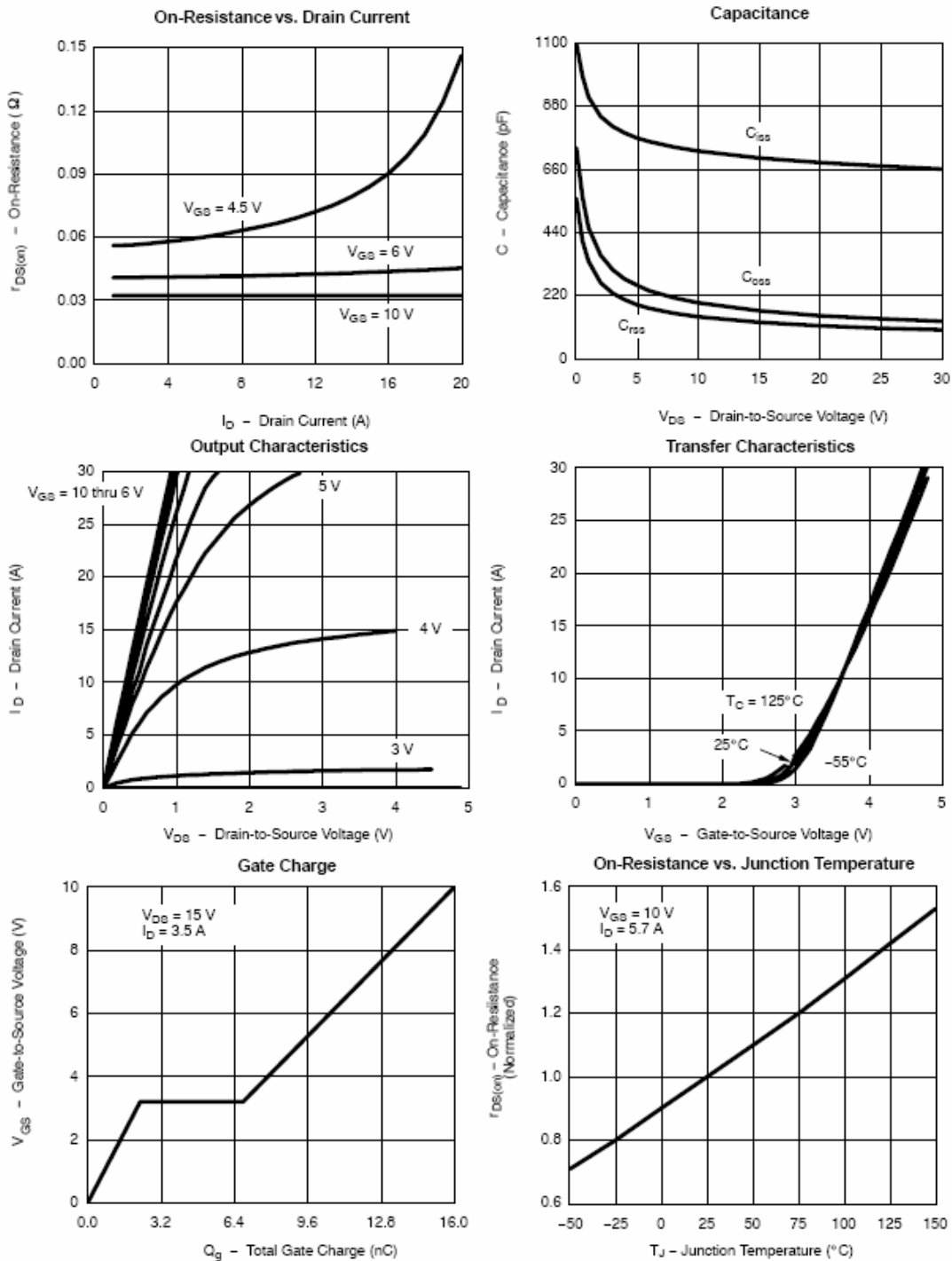
**❖ ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  Unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0		-3.0	V
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-30V, V_{GS}=0V$			-1	$\mu A$
		$V_{DS}=-30V, V_{GS}=0V$ $T_J=55^\circ C$			-5	
$I_{D(ON)}$	On-State Drain Current	$V_{DS} \leq -5V, V_{GS} \leq -10V$	-25			A
$R_{DS(ON)}$	Drain-source On-Resistance	$V_{GS}=-10V, I_D=-5.2A$ $V_{GS}=-4.5V, I_D=-4.5A$		45 60	60 90	$m\Omega$
$G_{fs}$	Forward Transconductance	$V_{DS}=-10V, I_D=-5.2A$		10		S
<b>Source-Drain Diode</b>						
$I_S$	Diode forward Current (Max.)				2.6	A
$V_{SD}$	Diode Forward Voltage	$I_S=-2.0A, V_{GS}=0V$		-0.8	-1.2	V
<b>Dynamic Parameters</b>						
$Q_g$	Total Gate Charge	$V_{DS}=-15V, V_{GS}=-10V$ $I_D=-5.0A$		15	10	nC
$Q_{gs}$	Gate-Source Charge			4.0		
$Q_{gd}$	Gate-Drain Charge			2.0		
$C_{iss}$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V$ $f=1MHz$		680		pF
$C_{oss}$	Output Capacitance			120		
$C_{rss}$	Reverse Transfer Capacitance			75		
$t_{d(on)}$	Turn-On Time	$V_{DD}=-15V, R_L=15\Omega$ $I_D=-1.0A, V_{GEN}=-10V$ $R_G=6\Omega$		7.0	15	nS
$t_r$				10	20	
$t_{d(off)}$	Turn-Off Time			40	80	
$t_f$				20	40	

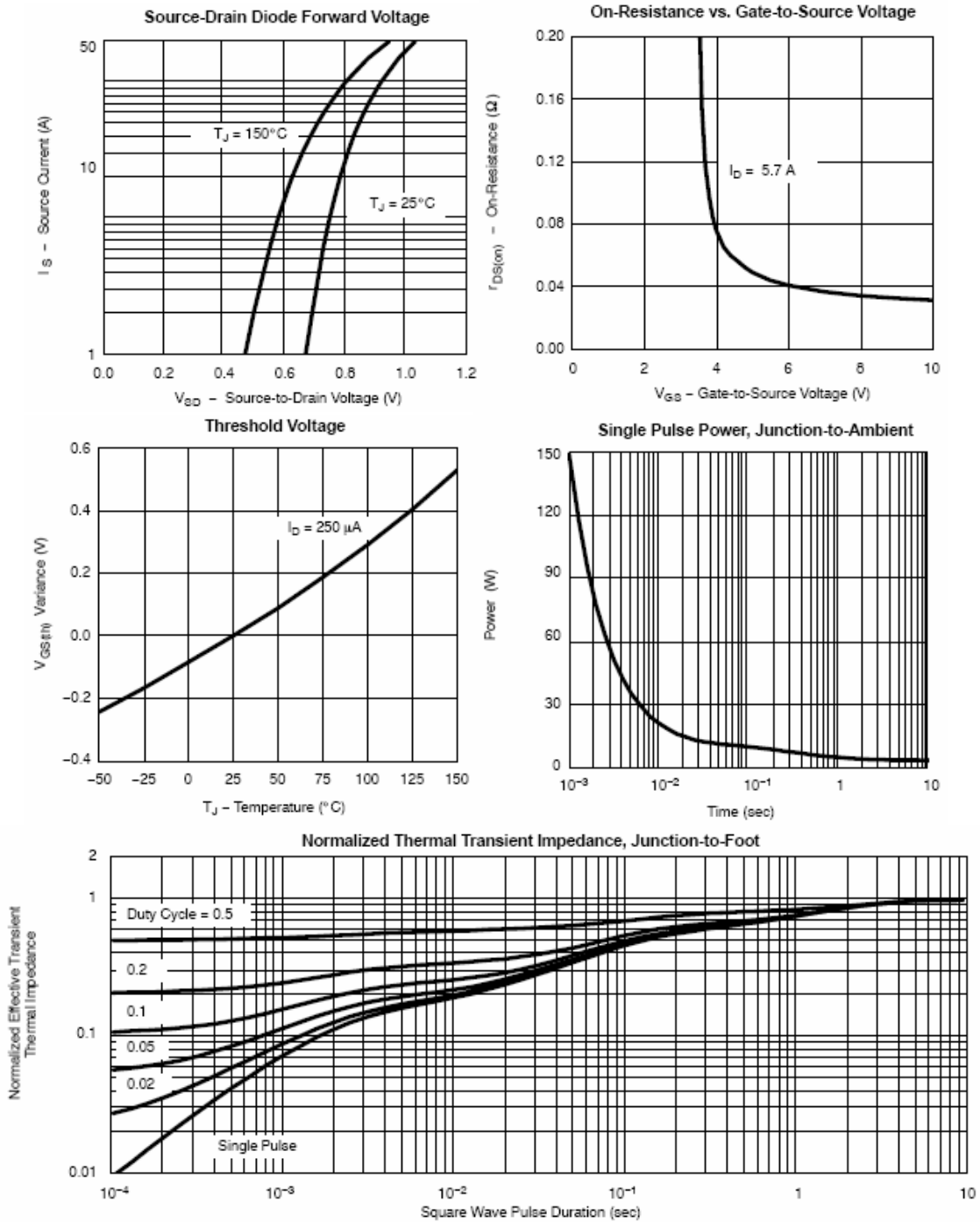
Note : 1. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$

2. Static parameters are based on package level with recommended wire-bonding

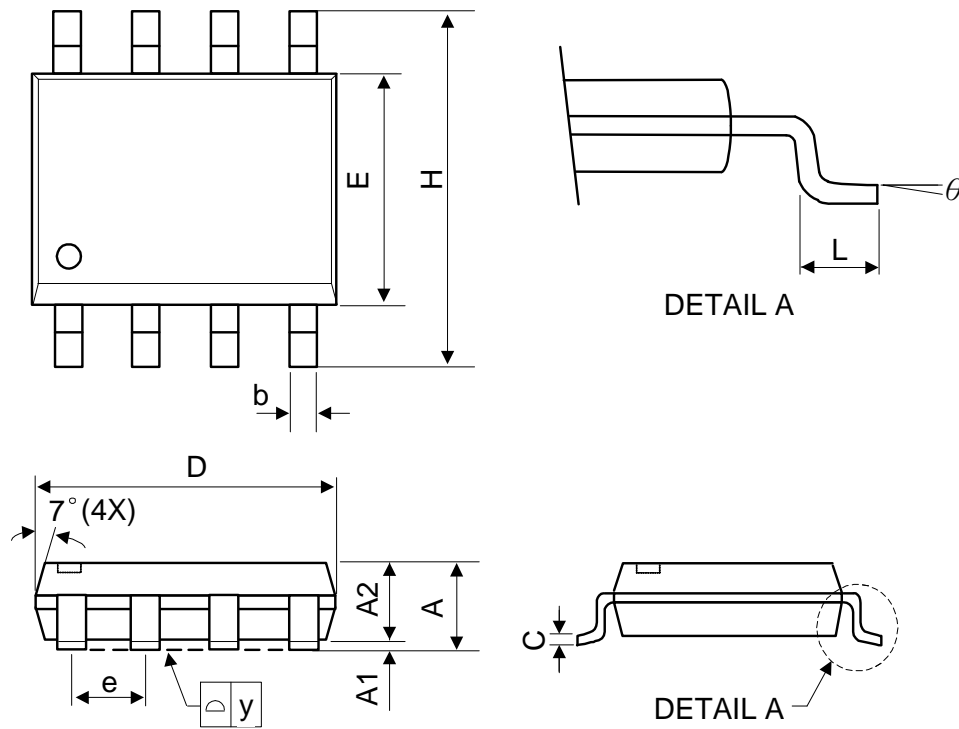
❖ TYPICAL CHARACTERISTICS (25°C Unless Note)



❖ TYPICAL CHARACTERISTICS (25°C Unless Note)



❖ PACKAGE OUTLINES



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	1.75	-	-	0.069
A1	0.1	-	0.25	0.04	-	0.1
A2	1.25	-	-	0.049	-	-
C	0.1	0.2	0.25	0.0075	0.008	0.01
D	4.7	4.9	5.1	0.185	0.193	0.2
E	3.7	3.9	4.1	0.146	0.154	0.161
H	5.8	6	6.2	0.228	0.236	0.244
L	0.4	-	1.27	0.015	-	0.05
b	0.31	0.41	0.51	0.012	0.016	0.02
e	1.27 BSC			0.050 BSC		
y	-	-	0.1	-	-	0.004
$\theta$	0°	-	8°	0°	-	8°

Mold flash shall not exceed 0.25mm per side  
JEDEC outline: MS-012 AA